

NCE N-Channel Enhancement Mode Power MOSFET

Description

The NCE0140IA uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

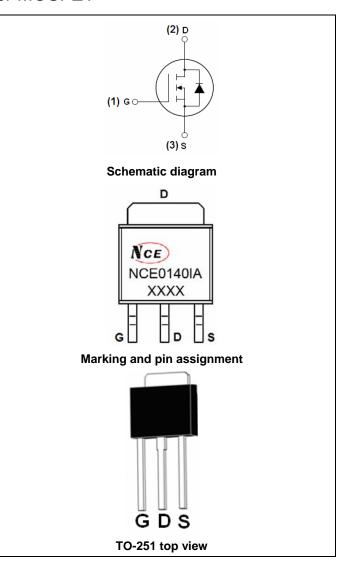
- V_{DS} = 100V, I_{D} =40A $R_{DS(ON)}$ < 17mΩ @ V_{GS} =10V (Typ:14mΩ)
- Special process technology for high ESD capability
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation

Application

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

100% UIS TESTED!

100% AVds TESTED!



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE0140IA	NCE0140IA	TO-251	-	-	-

Absolute Maximum Ratings (T_C=25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	100	V
Gate-Source Voltage	V _{GS}	±20	V
Drain Current-Continuous	I _D	40	Α
Drain Current-Continuous(T _C =100 °C)	I _D (100℃)	28	Α
Pulsed Drain Current	I _{DM}	160	А
Maximum Power Dissipation	P _D	140	W
Derating factor	-	0.94	W/°C
Single pulse avalanche energy (Note 5)	E _{AS}	520	mJ
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 175	$^{\circ}$ C



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Thermal Characteristic

Thermal Resistance, Junction-to-Case ^(Note 2)	$R_{ heta JC}$	1.07	°C/W	
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Electrical Characteristics (T_C=25°C unless otherwise noted)

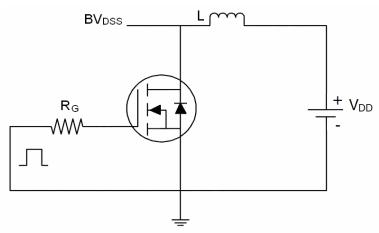
Parameter	Symbol Condition		Min	Тур	Max	Unit
Off Characteristics	<u>.</u>					
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	100	110	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =100V,V _{GS} =0V	-	-	1	μΑ
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)						•
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$, $I_{D}=250\mu A$	0.9	1.1	1.5	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =28A	-	14	17	mΩ
Forward Transconductance	g Fs	V _{DS} =25V,I _D =28A	32	-	-	S
Dynamic Characteristics (Note4)		,		l .		l.
Input Capacitance	C _{lss}	\\ 00\\\\ 0\\	-	3400	-	PF
Output Capacitance	Coss	V _{DS} =30V,V _{GS} =0V,	-	290	-	PF
Reverse Transfer Capacitance	C _{rss}	F=1.0MHz	-	221	-	PF
Switching Characteristics (Note 4)						•
Turn-on Delay Time	t _{d(on)}		-	15	-	nS
Turn-on Rise Time	t _r	VDD=30V,ID=2A,RL=15Ω,	-	11	-	nS
Turn-Off Delay Time	$t_{d(off)}$	RG=2.5Ω,VGS=10V	-	52	-	nS
Turn-Off Fall Time	t _f		-	13	-	nS
Total Gate Charge	Qg		-	94	-	nC
Gate-Source Charge	Q_{gs}	ID=30A,VDD=30V,VGS=10V	-	16	-	nC
Gate-Drain Charge	Q_{gd}		-	24	-	nC
Drain-Source Diode Characteristics	1	,		l .		•
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =28A	-	0.85	1.2	V
Diode Forward Current (Note 2)	Is		-	-	40	Α
Reverse Recovery Time	t _{rr}	TJ = 25°C, IF = 28A	-	33		nS
Reverse Recovery Charge	Qrr	di/dt = 100A/µs ^(Note3)	-	54		nC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

Notes:

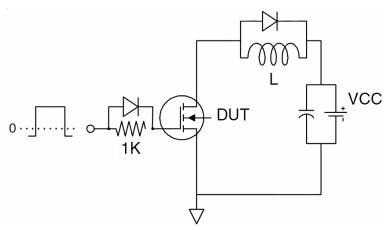
- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- **3.** Pulse Test: Pulse Width ≤ 300μ s, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production
- **5.** EAS condition: Tj=25 $^{\circ}$ C,V_{DD}=50V,V_G=10V,L=0.5mH,Rg=25 Ω

Test Circuit

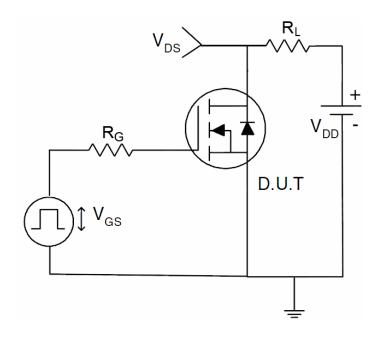
1) E_{AS} test Circuit



2) Gate charge test Circuit



3) Switch Time Test Circuit





Typical Electrical and Thermal Characteristics (Curves)

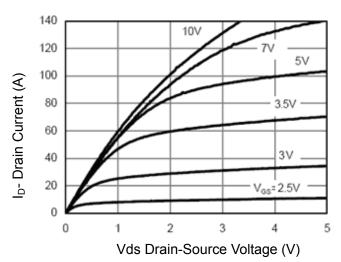


Figure 1 Output Characteristics

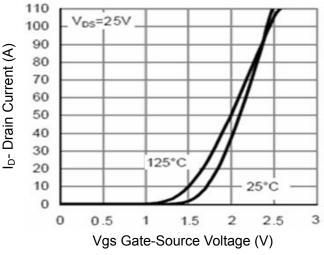


Figure 2 Transfer Characteristics

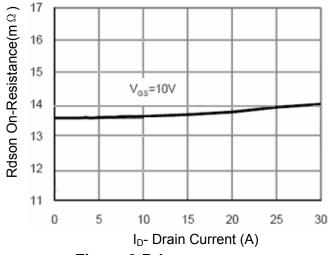


Figure 3 Rdson- Drain Current

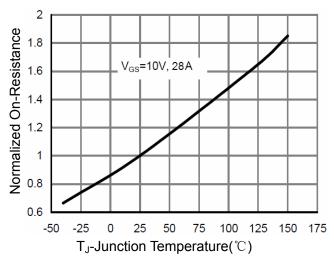


Figure 4 Rdson-JunctionTemperature

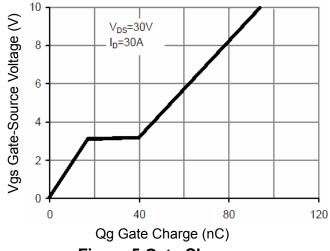


Figure 5 Gate Charge

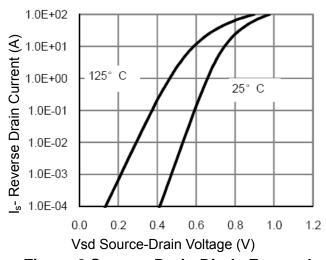


Figure 6 Source- Drain Diode Forward

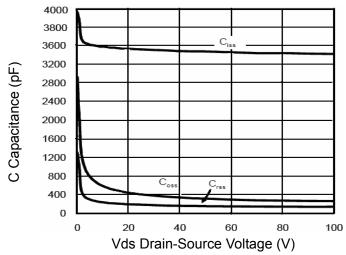


Figure 7 Capacitance vs Vds

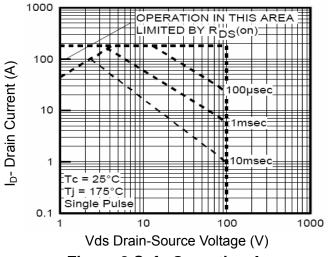


Figure 8 Safe Operation Area

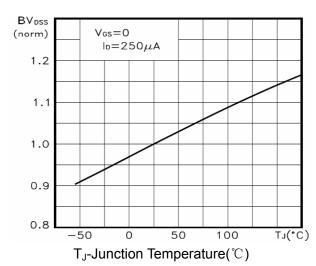


Figure 9 BV_{DSS} vs Junction Temperature

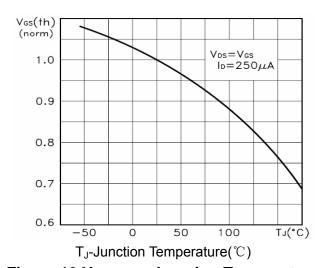


Figure 10 V_{GS(th)} vs Junction Temperature

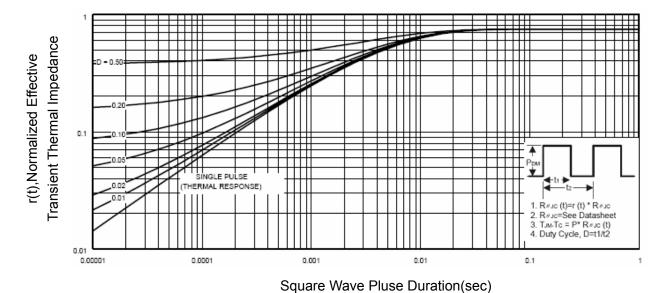
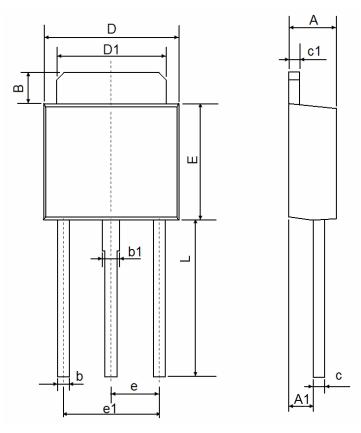


Figure 11 Normalized Maximum Transient Thermal Impedance





TO-251 Package Information



Symbol	Dimensions	In Millimeters	Dimensions In Inches		
	Min.	Max.	Min.	Max.	
Α	2.200	2.400	0.087	0.094	
A1	1.050	1.350	0.042	0.054	
В	1.350	1.650	0.053	0.065	
b	0.500	0.700	0.020	0.028	
b1	0.700	0.900	0.028	0.035	
С	0.430	0.580	0.017	0.023	
c1	0.430	0.580	0.017	0.023	
D	6.350	6.650	0.250	0.262	
D1	5.200	5.400	0.205	0.213	
E	5.400	5.700	0.213	0.224	
е	2.300 TYP		0.091	TYP	
e1	4.500	4.700	0.177	0.185	
L	7.500	7.900	0.295	0.311	



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